



#### **Scope of the Conference**

This virtual conference aims to bring researchers, academicians, and engineers to a single interactive platform. Through this conference, the participants from interdisciplinary fields can discuss their ideas, disseminate the latest research trends in new materials, processing, innovations, product design, and developments.

### **Topics include**

**Energy Harvesting and Storage Materials** 

**Biomedical Materials and Applications** 

Smart Materials for Sensor / Actuator Applications

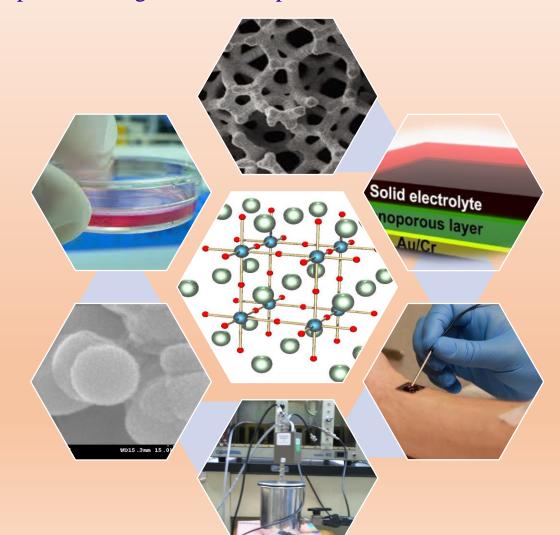
Functional and Hybrid Materials

Nanostructured Materials & Their Applications

Materials for Clean and Sustainable Technology

Coatings and Membranes

Crystal Growth and Crystallography



## Plenary speakers



Dr. S Kumar
University of Glasgow
United Kingdom



Dr. Evgeny V. Parfenov USATU, Russia





Dr. Hans-Uwe Dahms
Kaohsiung Medical University,
Taiwan



**Dr. S. Narayana Kalkura**Anna University, **Chennai, India** 



Dr. D. Arivuoli
Anna University, Chennai, India



Dr. P. Murugavel
IIT Madras, Chennai, India



Dr. John V Kennedy
GNS Science, New
Zealand

#### **CONFERENCE COMMITTEE**

#### **CORE COMMITTEE.**

Faculty Members of The Department of Physics, NITT







Dr. J. Hemalatha



Dr. R. Arthur James



Dr. E. K. Girija



Dr. N. Meenakshi Sundaram



Dr. Elayaraja Kolanthai

#### **ORGANISING TEAM**





Dr. M. Ashok Chairman



Dr. N. Ramesh Babu Secretary



Dr. D. Sastikumar Co-Chairman



#### **Expected Contributors**

**Research scholars** 

**Academicians** 

**Research scientists** 

**Practicing Engineers** 



#### **Modes of Contribution**

Online paper presentation

Online poster presentation

Participation without presentation

#### **Important Dates**

Abstract submission deadline – Jan 31, 2021

Notification of acceptance - Feb 20, 2021

Fee Payment deadline – March 7, 2021

Paper submission deadline – March 7, 2021

Conference dates – March 11-13, 2021

#### **Registration Fee:**

Rs.250 (Indian)/\$10 (foreign)

# LINK FOR ABSTRACT SUBMISSION

Selected manuscript will be published in **SCOPUS/SCIE** Indexed Journals



